

FK4B01120L1

Single N-channel MOS FET

For Load switching circuits

■ Features

- Low Drain-source ON resistance: $R_{DS(on)}$ typ. = $17\text{m}\Omega$ ($V_{GS} = 2.5\text{ V}$)
- CSP (Chip Size Package)
- RoHS compliant (EU RoHS / MSL: Level 1 compliant)

■ Marking Symbol: 1C

■ Packaging

Embossed type (Thermo-compression sealing) : 1 000 pcs / reel (standard)

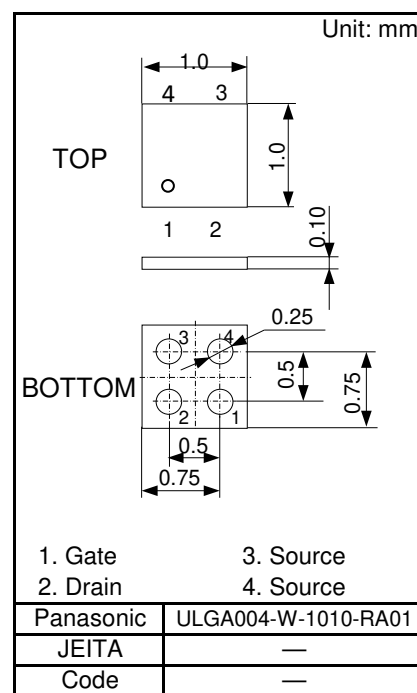
■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|----------------------|------------|------------------|
| Drain-Source Voltage | VDS | 12 | V |
| Gate-Source Voltage | VGS | ± 8 | V |
| Drain Current | ID1 ^{*1} | 3.9 | A |
| | ID2 ^{*2} | 6.5 | |
| | ID3 ^{*3} | 7.9 | |
| Peak Drain Current | IDp1 ^{*1*4} | 31 | A |
| | IDp2 ^{*2*4} | 52 | |
| | IDp3 ^{*3*4} | 63 | |
| Power Dissipation | PD1 ^{*1} | 0.37 | W |
| | PD2 ^{*2} | 0.94 | |
| | PD3 ^{*3} | 1.5 | |
| Channel Temperature | Tch | 150 | $^\circ\text{C}$ |
| Operating Ambient Temperature | Topr | -40 ~ +85 | $^\circ\text{C}$ |
| Storage Temperature | Tstg | -55 ~ +150 | $^\circ\text{C}$ |

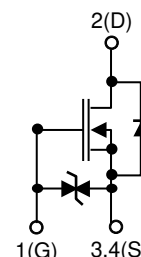
Note *1 FR4 board (25.4mm×25.4mm×t1.0mm), Min Cu 36mm² Copper

*2 FR4 board (25.4mm×25.4mm×t1.0mm), Full Cu

*3 Ceramic substrate (70mm×70mm×t1.0mm)

*4 t = 10 μs , Duty Cycle < 1%

■ Internal Connection



■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|---------|---|-----|-----|-----|------|
| Drain-Source Breakdown Voltage | VDSS | ID = 1 mA, VGS = 0 | 12 | | | V |
| Zero Gate Voltage Drain Current | IDSS | VDS = 12 V, VGS = 0 | | | 10 | μA |
| Gate-Source Leakage Current | IGSS | VGS = ±8 V, VDS = 0 V | | | ±10 | μA |
| Gate Threshold Voltage | Vth | ID = 394 μA, VDS = 10 V | 0.3 | | 1.0 | V |
| Drain-Source ON Resistance | RDS(on) | ID = 1.5 A, VGS = 4.5 V | | 14 | 24 | mΩ |
| | | ID = 1.0 A, VGS = 2.5 V | | 17 | 27 | |
| | | ID = 0.5 A, VGS = 1.8 V | | 21 | 36 | |
| | | ID = 0.25 A, VGS = 1.5 V | | 27 | 62 | |
| Input Capacitance ^{*1} | Ciss | VDS = 10 V | | 490 | | pF |
| Output Capacitance ^{*1} | Coss | VGS = 0 | | 184 | | |
| Reverse Transfer Capacitance ^{*1} | Crss | f = 1MHz | | 128 | | |
| Turn-on delay time ^{*1,*2} | td(on) | VDD = 6 V VGS = 0 to 4.5 V ID = 1.0 A | | 4.3 | | |
| Rise time ^{*1,*2} | tr | | | 3.7 | | |
| Turn-off delay time ^{*1,*2} | td(off) | | | 235 | | |
| Fall time ^{*1,*2} | tf | | | 147 | | |
| Total Gate Charge ^{*1} | Qg | VDD = 6 V | | 7 | | nC |
| Gate to Source Charge ^{*1} | Qgs | VGS = 4.5 V | | 1.4 | | nC |
| Gate to Drain Miller Charge ^{*1} | Qgd | ID = 1.0 A | | 1.5 | | nC |
| Body Diode Forward Voltage | VF(D-S) | IF = 0.2A, VGS = 0V | | 0.6 | 1.2 | V |

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

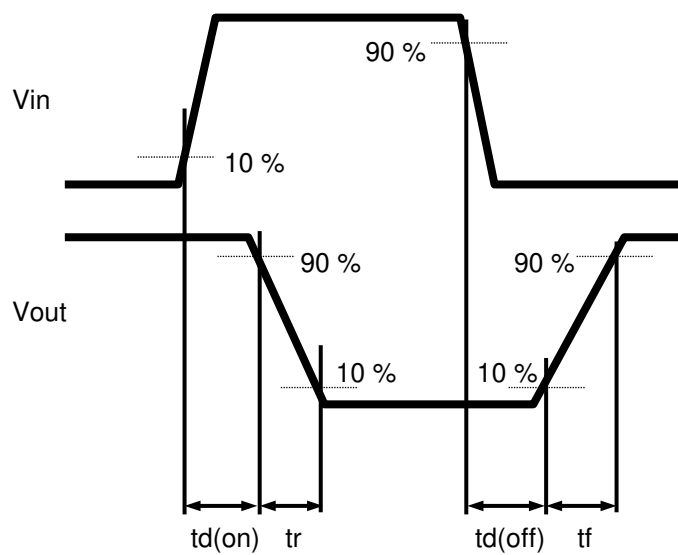
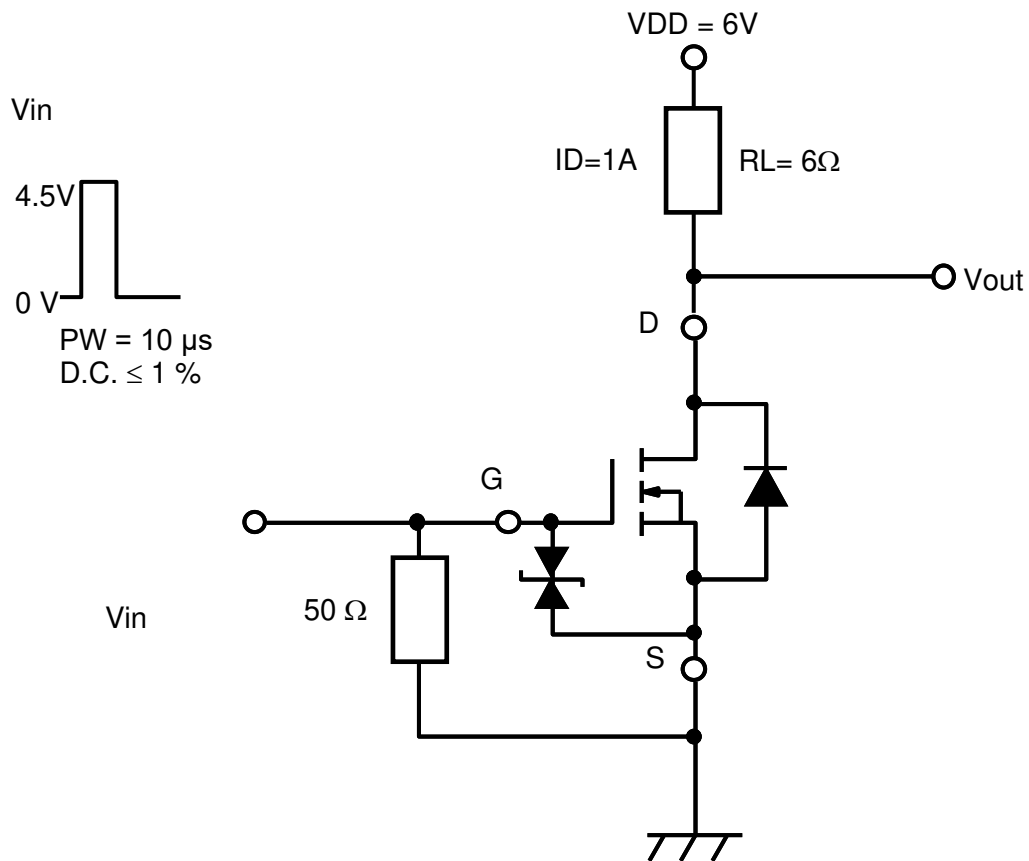
*1 Guaranteed by design, not subject to production testing

*2 Measurement circuit for Turn-on delay time / Rise time / Turn-off delay time / Fall time

■ Electrical State Discharge Characteristics

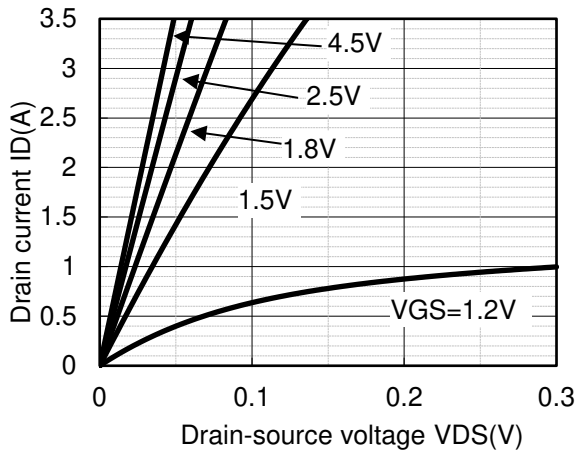
| Standard | Test Type | Symbol | Conditions | Class | Value | Unit |
|--------------|------------------|--------|------------------------|-------|---------------|------|
| AEC-Q101-001 | Human body model | HBM | C = 100 pF, R = 1.5 kΩ | H2 | >2k to ≤ 4k | V |
| | Machine model | MM | C = 200 pF, R = 0 Ω | M2 | >100 to ≤ 200 | V |

Note2: Measurement circuit

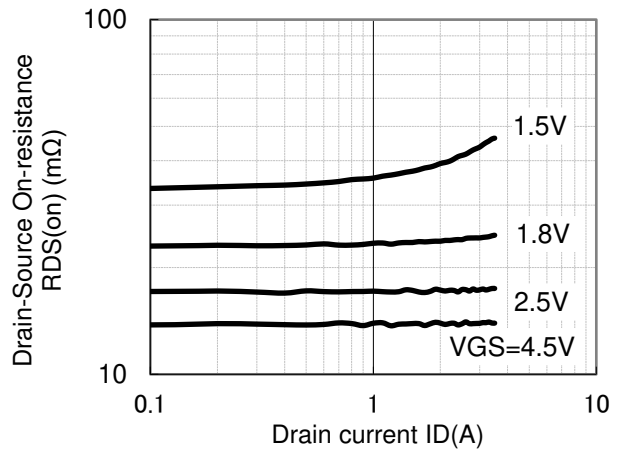




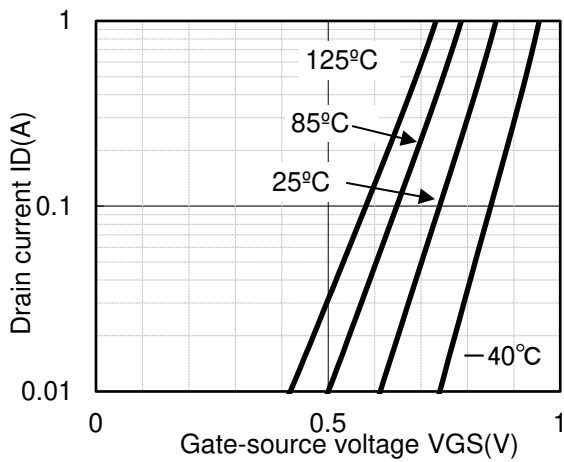
ID - VDS



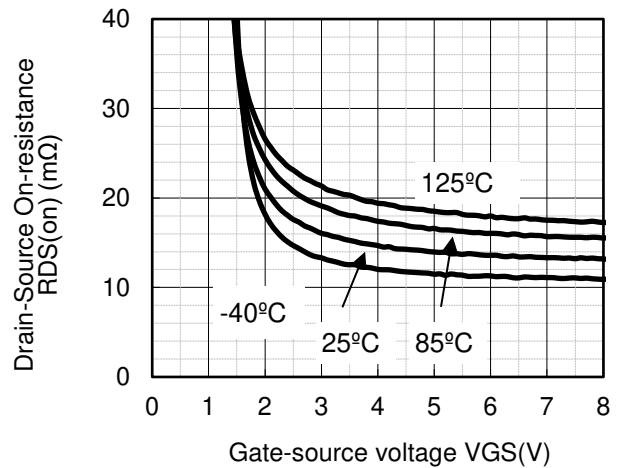
RDS(on) - ID



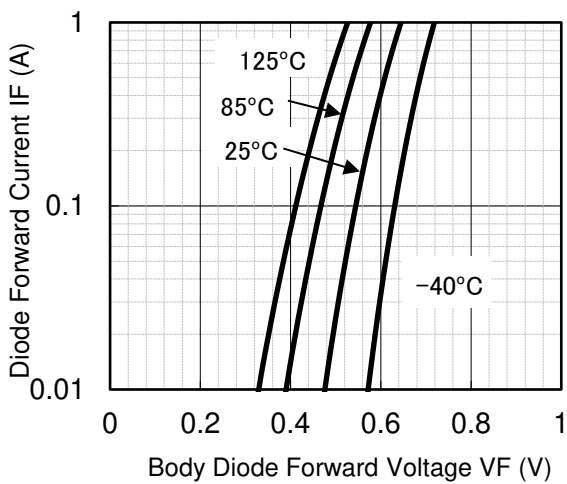
ID - VGS



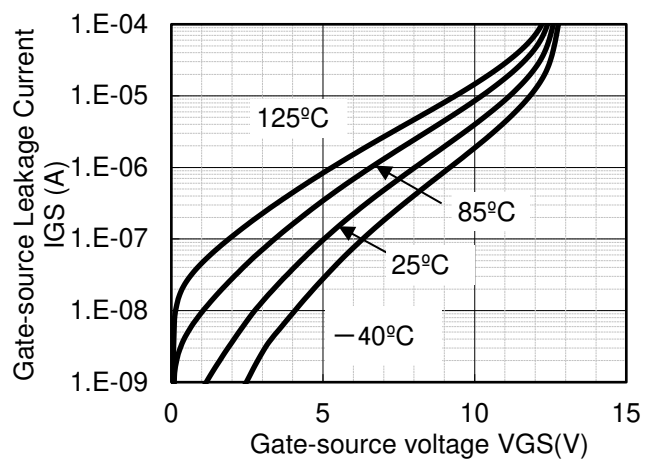
RDS(on) - VGS



IF - VF

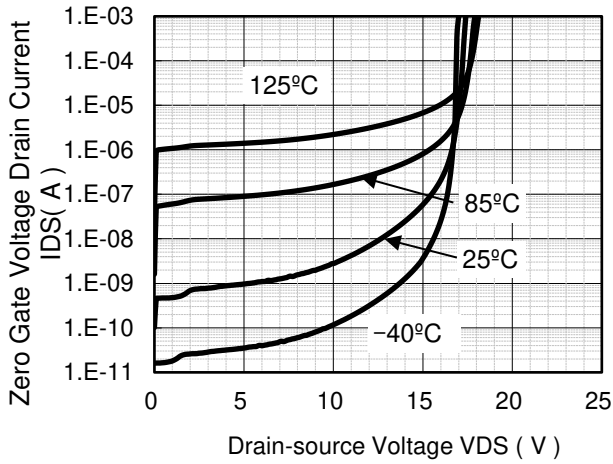


IGS - VGS

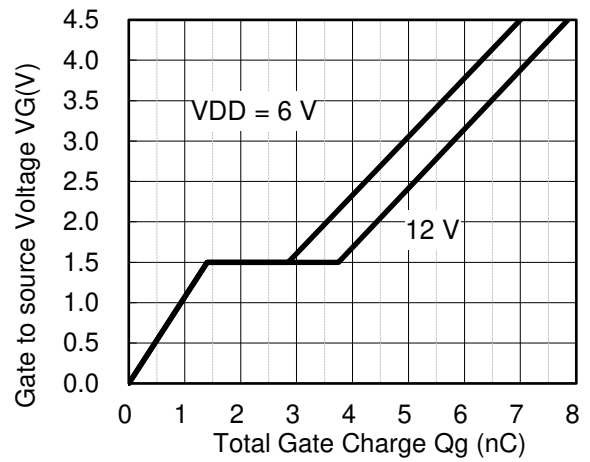




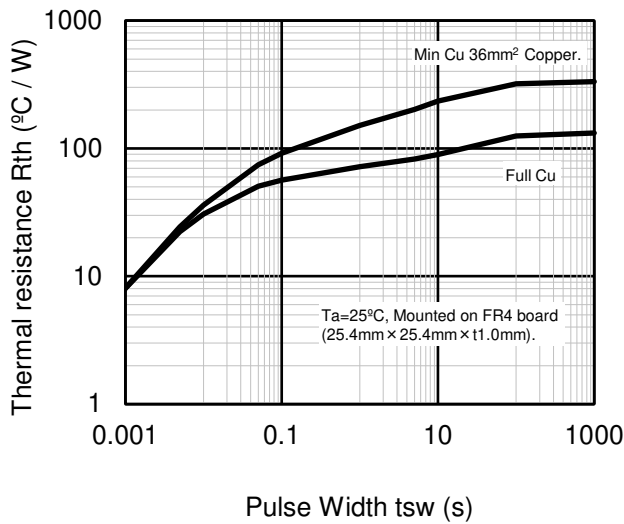
IDS - VDS



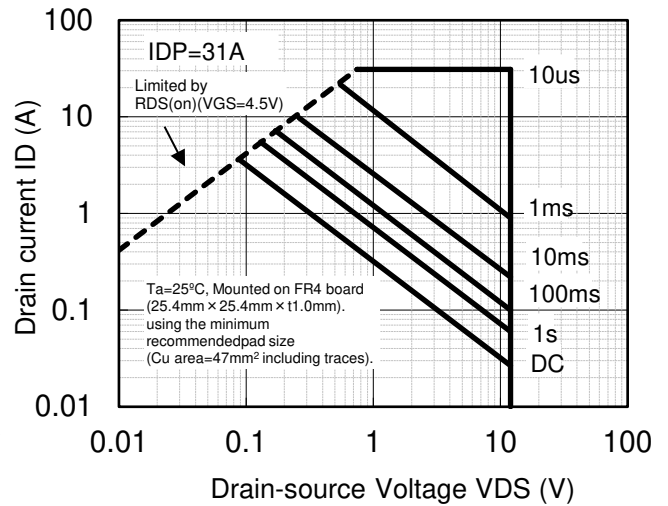
Dynamic Input/Output Characteristics



Rth - tsw

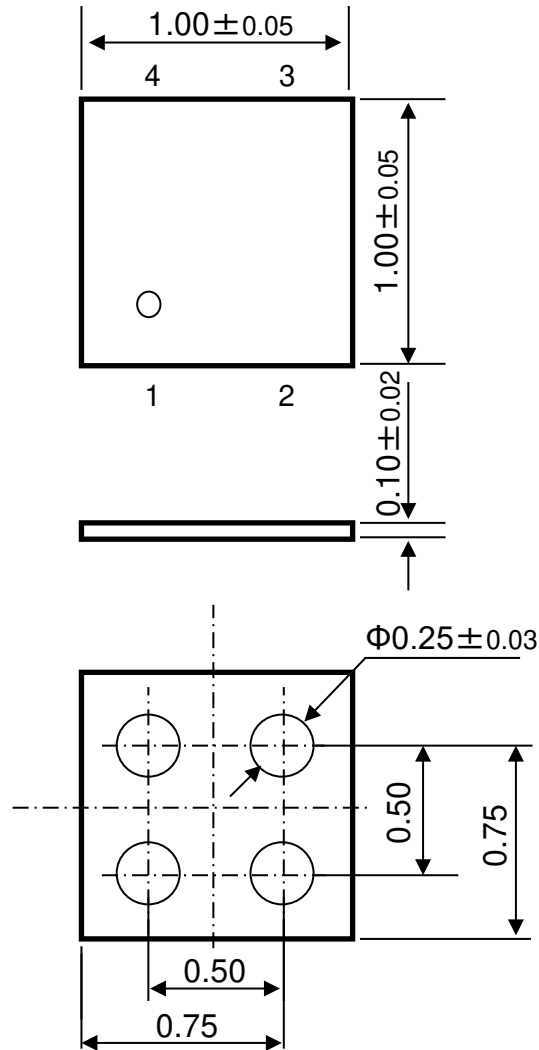


Safe Operating Area



■ ULGA004-W-1010-RA01

Unit: mm



■ Land Pattern (Reference)

